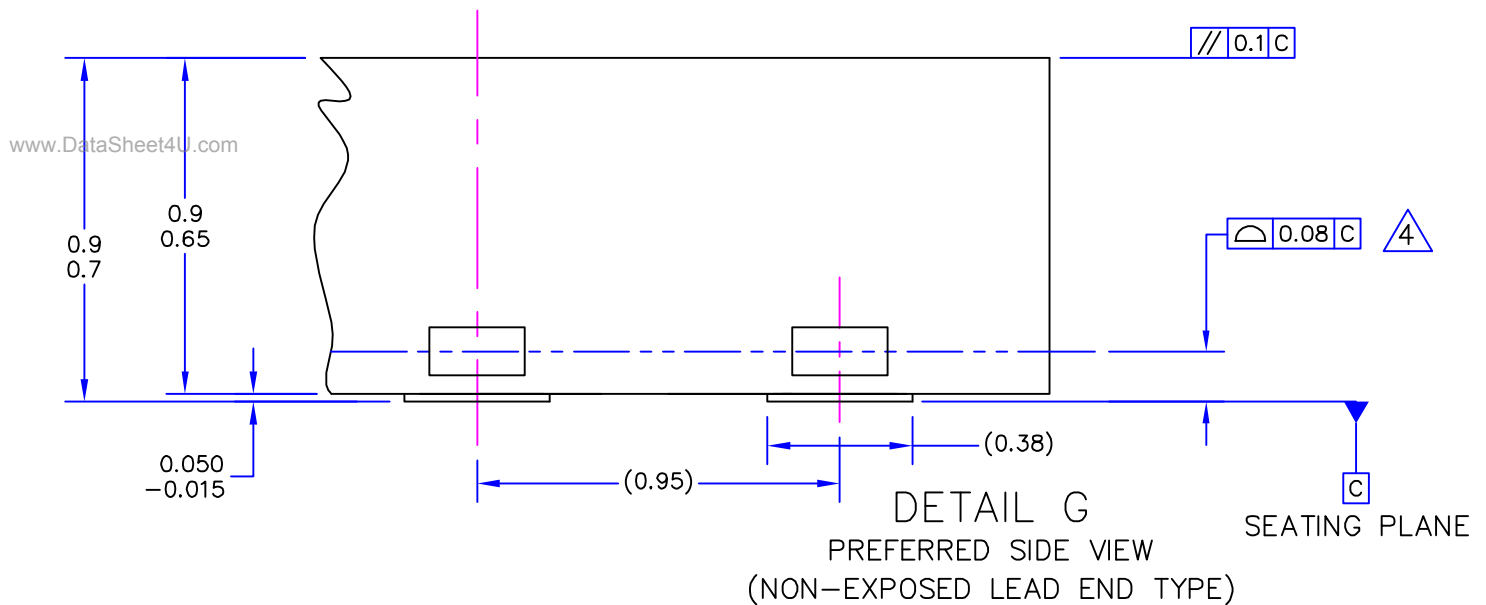
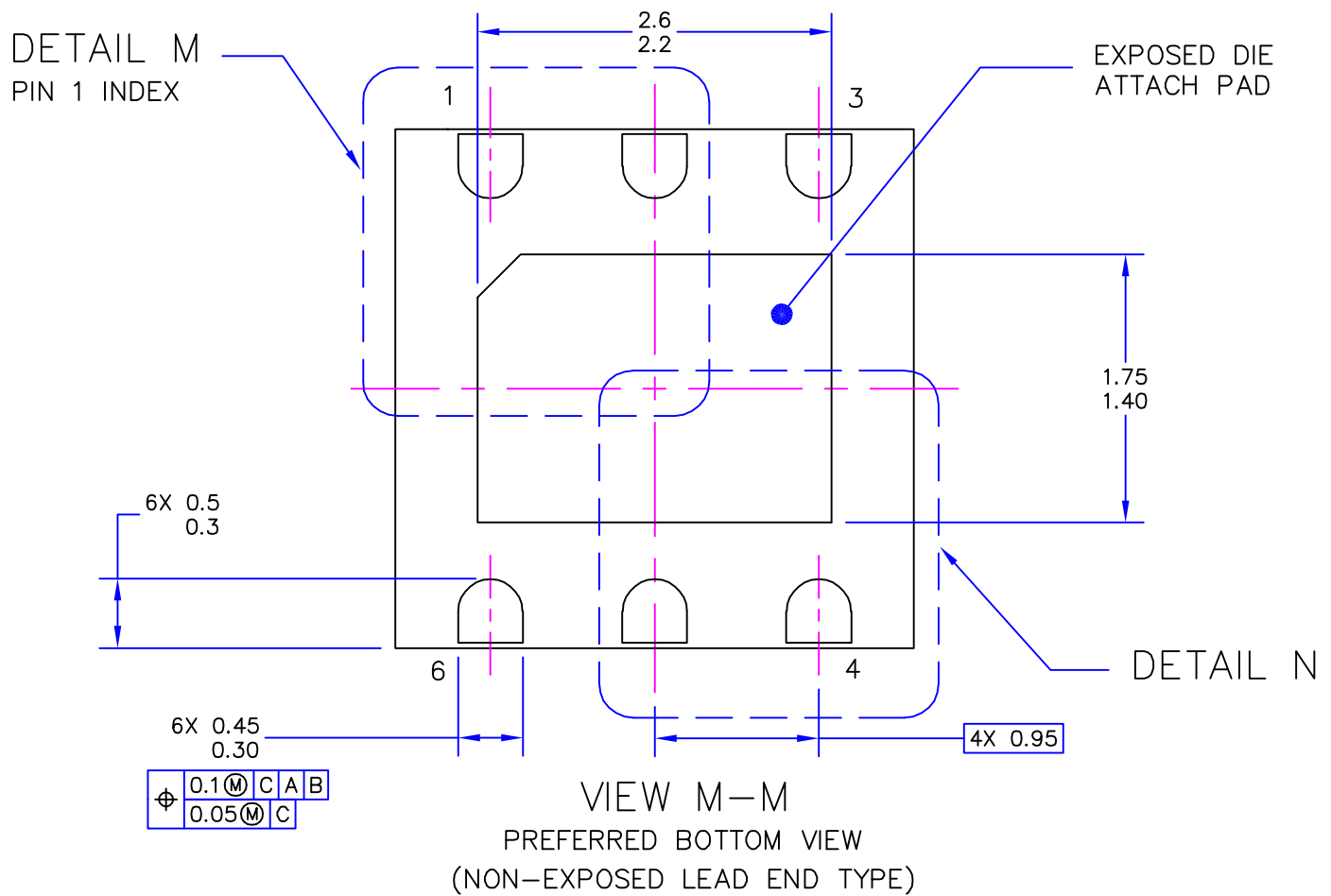
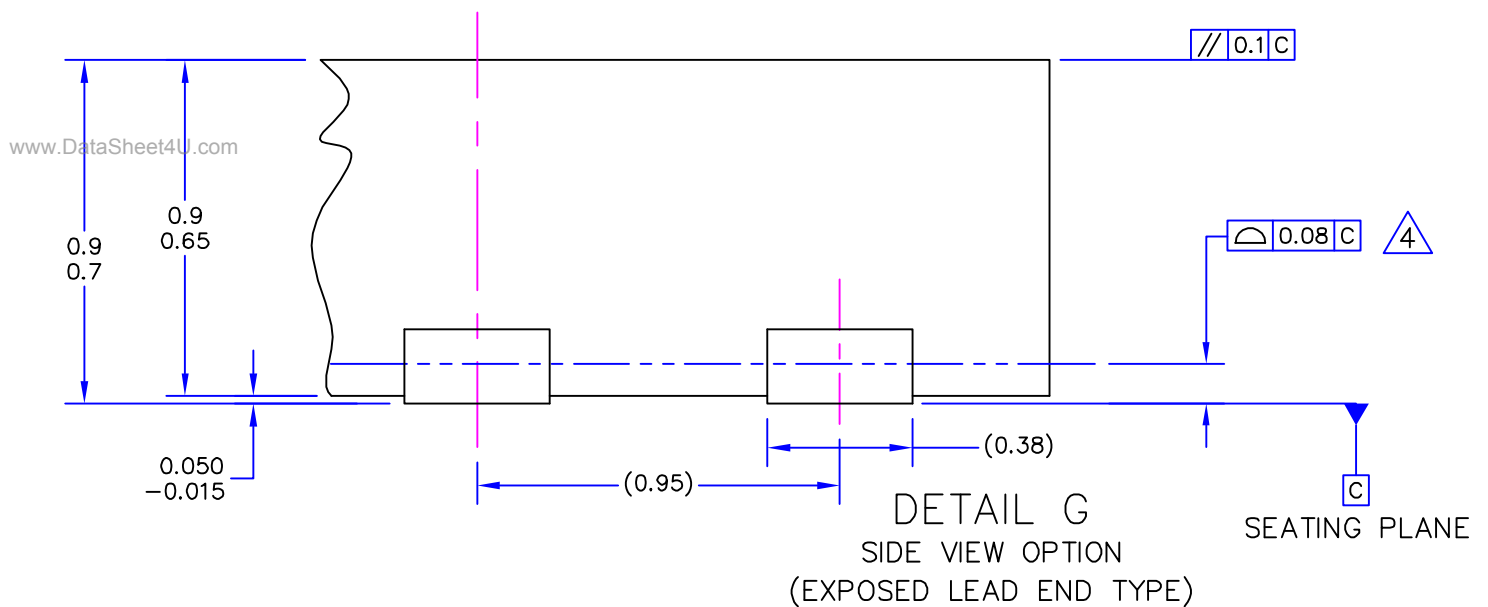
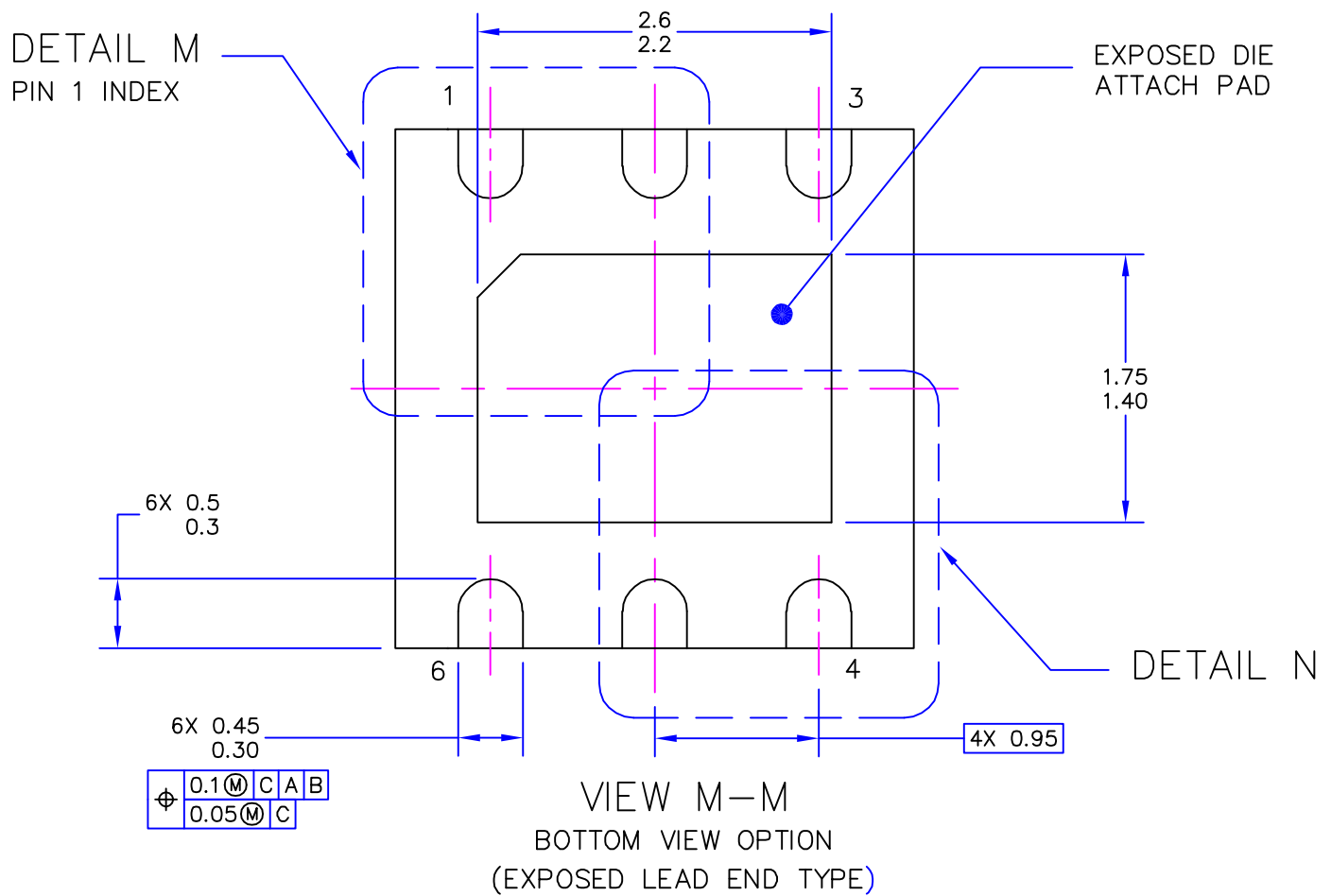




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TITLE: THERMALLY ENHANCED DUAL FLAT NON-LEADED PACKAGE (DFN) 6 TERMINAL, 0.95 PITCH (3 X 3 X 0.8)	DOCUMENT NO: 98ARL10602D		REV: C
	CASE NUMBER: 1677-02		16 DEC 2008
	STANDARD: FREESCALE STD		



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MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE: THERMALLY ENHANCED DUAL
FLAT NON-LEADED PACKAGE (DFN)
6 TERMINAL, 0.95 PITCH (3 X 3 X 0.8)

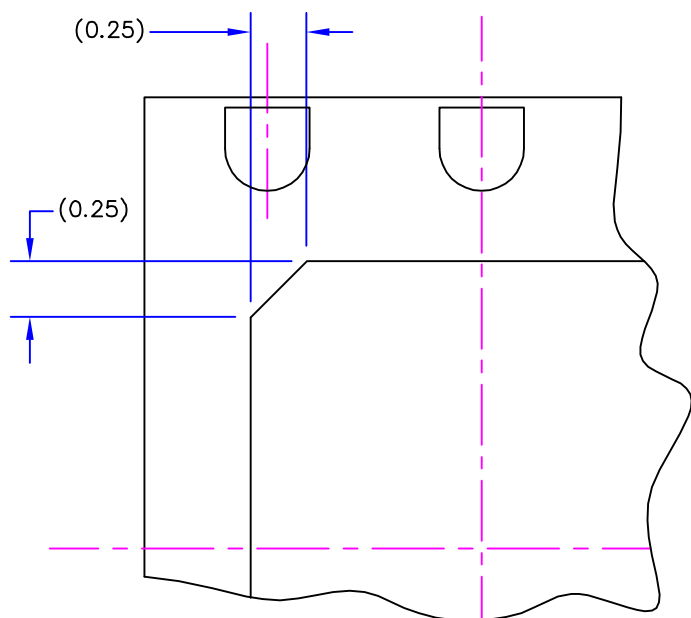
DOCUMENT NO: 98ARL10602D

REV: C

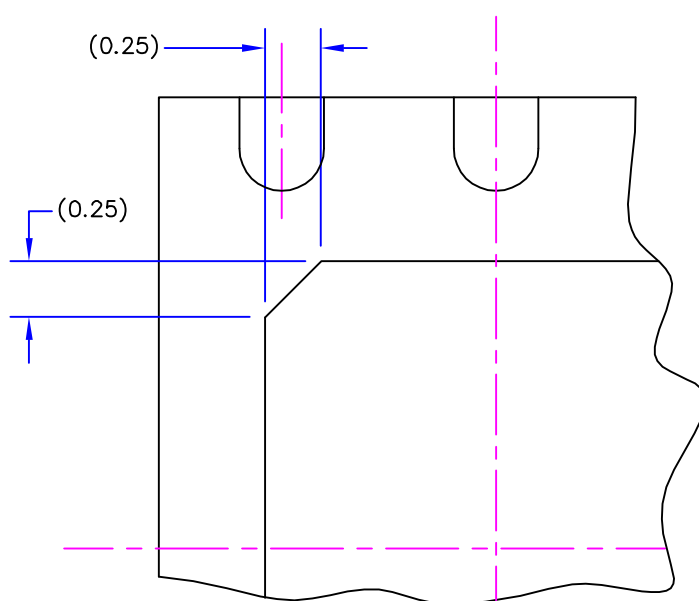
CASE NUMBER: 1677-02

16 DEC 2008

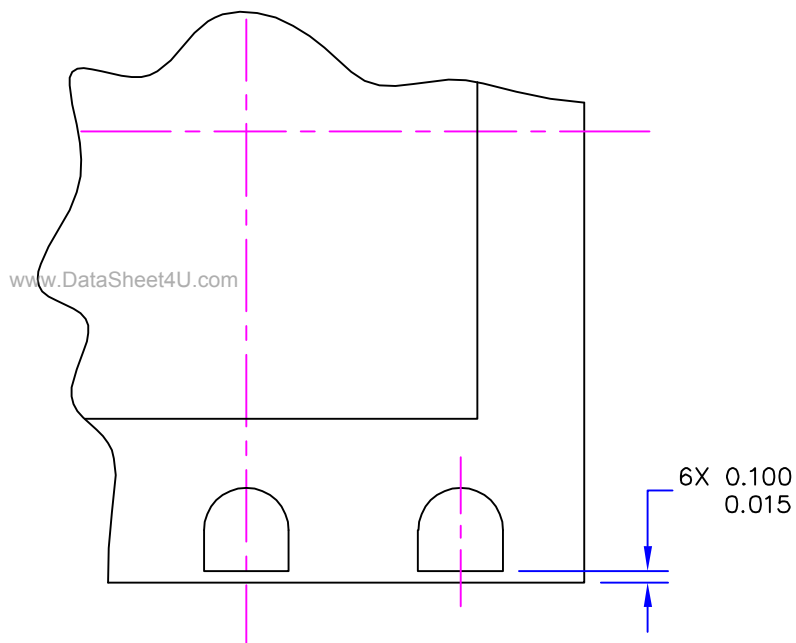
STANDARD: FREESCALE STD



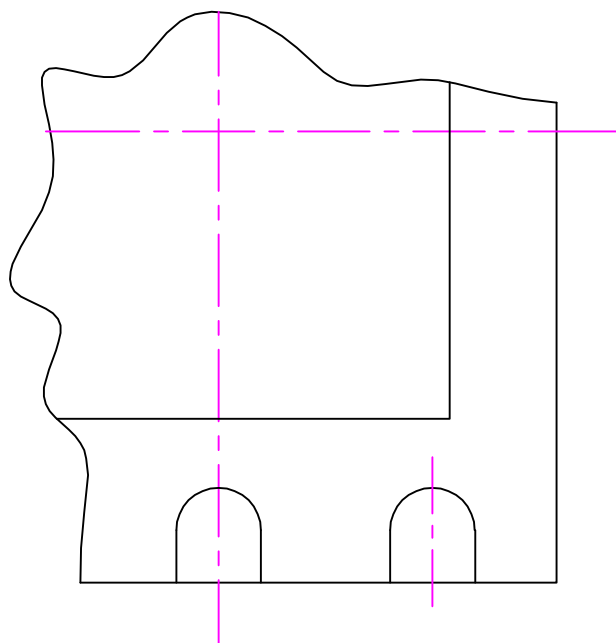
DETAIL M
PREFERRED BACKSIDE PIN 1 INDEX



DETAIL M
BACKSIDE PIN 1 INDEX OPTION



DETAIL N
PREFERRED CORNER CONFIGURATION



DETAIL N
CORNER CONFIGURATION OPTION

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	CASE NUMBER: 1677-02		16 DEC 2008	
	STANDARD: FREESCALE STD			

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M–1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HV–PDSO–N.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

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